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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: JOHN M. PEDERSEN ET AL.

APPLICATION No.: 09/823,948

FILED: MARCH 30, 2001

FOR: **DRY CONTACT ASSEMBLIES, METHODS
FOR MAKING DRY CONTACT
ASSEMBLIES, AND PLATING MACHINES
WITH DRY CONTACT ASSEMBLIES FOR
PLATING MICROELECTRONIC
WORKPIECES**

EXAMINER: BRIAN L. MUTSCHLER

ART UNIT: 1753

CONF. No: 7598

10/C
W.M.
6/11/03

Amendment in Response to Restriction Requirement

RECEIVED

JUN 09 2003

TC 1700

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated April 30, 2003, please amend the application as reflected in the following listing of claims.

Amendment to the Claims

1. (Original) A contact assembly for plating a layer on a microelectronic workpiece, comprising:

C1
a support member having an opening configured to receive a microelectronic workpiece;

a contact system carried by the support member, the contact system having a plurality of electrically conductive contact members projecting inwardly into the opening;

a shield carried by the support member to prevent electroplating solution from engaging the contact members, the shield projecting from the support member to